

- . Integrated pressure sensor
- . 300-1100hPa absolute Pressure Range
- . 16 Bit Σ - Δ ADC
- . 11 coefficients for software compensation stored on chip
- . I²C Serial Interface
- . One system clock line (32768Hz)
- . One hardware controlled reset line
- . Low voltage, low power consumption

Description

The HP03M pressure module includes a piezo-resistive pressure sensor and an ADC interface. It provides 16 bit word data for pressure and temperature related voltage. With the help of a highly accurate calibration of the sensor, 11 unique coefficients were stored on the chip, thus accurate pressure and temperature reading can be realized. HM03M is a low power, low voltage device with automatic power down switching. I²C Serial Interface is used for communications with a microprocessor. Sensor packaging options are DIP or SMD (with metal cap)

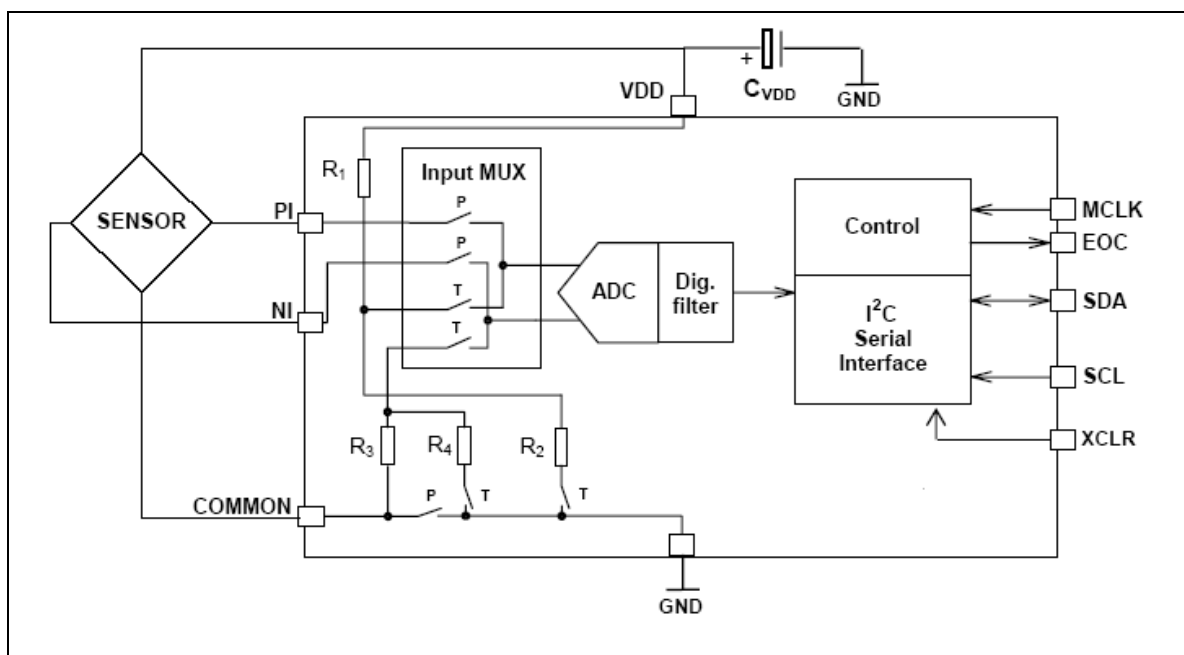
Features

- . 14 Bit ADC resolution
- . Supply voltage 2.2v-3.6v
- . -40°C to +85°C operating range
- . No external components required

Applications

- . Pressure measurement and control systems
- . Mobile altimeter/barometer systems
- . Weather forecast products
- . Adventure or multi-mode watches
- . GPS receivers

Block Diagram



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PIN Description

Pin Name	Pin Number	Type	Function
VSS	6	G	power ground
VDD	5	P	power VCC
MCLK	4	I	master clock(32k) input
XCLR	3	I	ADC reset input (keep low when system is in idle state)
SDA	2	I/O	I ² C data input and output
SCL	1	I	I ² C clock input

* XCLR is to reset the AD converter (active low). XCLR should be set to high only during AD conversion phase(reading D1,D2), at all other states, such as reading calibration factors, this pin should be kept low.

* The quality of the MCLK signal can significantly influence the current consumption of the pressure module. To obtain minimum current, remember to supply good quality MCLK signal

Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply Voltage	VDD	-0.3	4	V
Over pressure	P		15	Bar(abs)
Storage Temperature	Tstg	-40	125	°C

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	VDD		2.2	3	3.6	V
Supply Current	I	VDD=3V				V
during conversion				500		μA
Stand by				1		μA
Operating Pressure Range	P		300		1100	hPa (abs)
Operating Temperature Range	T		-40	25	85	°C
MCLK	T		30	32768	35	KHz
Duty Cycle of MCLK			40%	50%	60%	%
Serial Date Rate	SCL				500	KHz

Pressure and Temperature Output Characteristics

With the calibration data provided by the HP03 system, it should be able to reach the following characteristics:

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Absolute Pressure Accuracy		750-1100 @ 0~-50°C	-1.5		1.5	hPa
Absolute Pressure Accuracy		750-1100 @ -20~60°C	-3.0		3.0	hPa
Long Term Stability		12 month		2		hPa
VDD Dependency		2.4~3.6	-1.5	0	1.5	hPa
Temperature Accuracy		0~+50	-1.0		1.0	°C
Temperature Accuracy		-20~+60	-2.0		2.0	°C

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Pressure and Temperature Measurement

The main function of HP03 system is to convert the uncompensated pressure and temperature signal from a pressure sensor. After the conversion, the following two values can be obtained:

- . measured temperature “D2”
- . measured pressure “D1”

As the sensor is strongly temperature dependent, it is necessary to compensate for these effects. Therefore 10 sensor-specific coefficients are stored on the HP03 at our manufacturing facility, and they allow an accurate software compensation in the application.

The 7 coefficients are:

- . Sensitivity coefficient “C1”
- . Offset coefficient “C2”
- . Temperature Coefficient of Sensitivity “C3”
- . Temperature Coefficient of Offset “C4”
- . Reference Temperature “C5”
- . Temperature Coefficient of Temperature “C6”
- . Offset Fine Tuning “C7”

4 sensor parameter

- . Sensor Specific Parameter “A,B,C,D”

Note: Make sure to pull low XCLR before start to Read these coefficients or the data read out is probably incorrect

Parameter Range (Hex:Dec)	
C1	0x100 -- 0xFFFF : 256 -- 65535
C2	0x00 -- 0x1FFF ; 0 -- 8191
C3	0x00 -- 0x400 ; 0 -- 3000
C4	0x00 -- 0x1000 ; 0 -- 4096
C5	0x1000 -- 0xFFFF ; 4096 -- 65535
C6	0x00 -- 0x4000 ; 0 -- 16384
C7	0x960 -- 0xA28 ; 2400 -- 2600
C, D	0x01 -- 0x0F ; 1 -- 15
A, B	0x01 -- 0x3F ; 1 -- 63
D1	0x00 -- 0xFFFF ; 0 -- 65535
D2	0x00 -- 0xFFFF ; 0 -- 65535

Pressure and Temperature Calculation:

Step 1: (get temperature value)

$D2 \geq C5 \quad dUT = D2 - C5 - ((D2 - C5) / 2^7) * ((D2 - C5) / 2^7) * A / 2^C$ $D2 < C5 \quad dUT = D2 - C5 - ((D2 - C5) / 2^7) * ((D2 - C5) / 2^7) * B / 2^C$
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Step 2: (calculate offset, sensitivity and final pressure value)

$OFF = (C2 + (C4 - 1024) * dUT / 2^{14}) * 4$
$SENS = C1 + C3 * dUT / 2^{10}$
$X = SENS * (D1 - 7168) / 2^{14} - OFF$
$P = X * 10 / 2^5 + C7$

- For altitude measurement system, recommend to use $P = X * 100 / 2^5 + C7 * 10$
- So that better altitude resolution can be achieved

Step 3: (calculate temperature)

$T = 250 + dUT * C6 / 2^{16} - dUT / 2^D$

Example:

C1=29908
 C2=3724
 C3=312
 C4=441
 C5=9191
 C6=3990
 C7=2500
 A=1
 B=4
 C=4
 D=9

D1=30036
 D2=4107

$dUT = (4107 - 9191) - ((4107 - 9191) * (4107 - 9191) / 128^2) * 4 / 2^4 = -5478$

$OFF = (3724 + (441 - 1024) * (-5478) / 2^{14}) * 4 = 15675$

$SENS = 29908 + 312 * (-5478) / 2^{10} = 28238$

$X = 28238 * (30036 - 7168) / 2^{14} - 15675 = 23738$

$P = 23738 * 10 / 2^5 + 2500 = 9918 = 991.8hPa$

$T = 250 + (-5478) * 3990 / 2^{16} - (-5478 / 2^9) = -72 = -7.2^{\circ}C$

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Serial Interface

The I²C interface is used for accessing calibration data as well as reading measurement result from AD conversion.

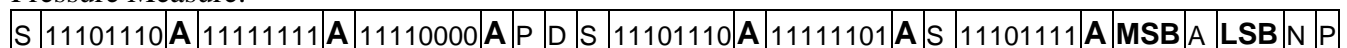
The EEPROM and ADC is sharing the same I²C bus but with different chip address assigned. The EEPROM chip address is set to 0xA1(in the case of read), write operation is not allowed. For AD part, the chip address is set to 0xEE. So this module used two different addresses for calibration data and AD converting data accessing. Calibration EEPROM data read operation is fully compatible to 24C02. Bus drive timing should be referred to the specification of this part as well.

Coefficient EEPROM ADDRESS

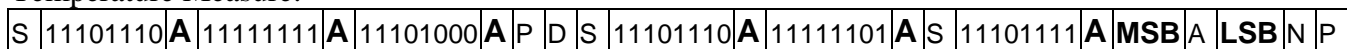
C1(MSB:LSB)	(16:17)
C2(MSB:LSB)	(18:19)
C3(MSB:LSB)	(20:21)
C4(MSB:LSB)	(22:23)
C5(MSB:LSB)	(24:25)
C6(MSB:LSB)	(26:27)
C7(MSB:LSB)	(28:29)
A	(30)
B	(31)
C	(32)
D	(33)

AD chip address is set to 0xEE(device write address), 0xEF(device read address). In order to get the AD value D1 and D2, you have to follow the following timing sequence:

Pressure Measure:



Temperature Measure:



- S: start condition
- P: stop condition
- A** (bold) : acknowledge from slave
- A : acknowledge from master
- N: no acknowledge from master (send out bit 1 instead)
- D : delay for 40ms minimum
- MSB: conversion result MSB
- LSB: conversion result LSB.

Remark:

Before start an AD conversion cycle, remember to pull high for XCLR pin so that the system is no longer in the reset state.

All data read from the module is in hex format.

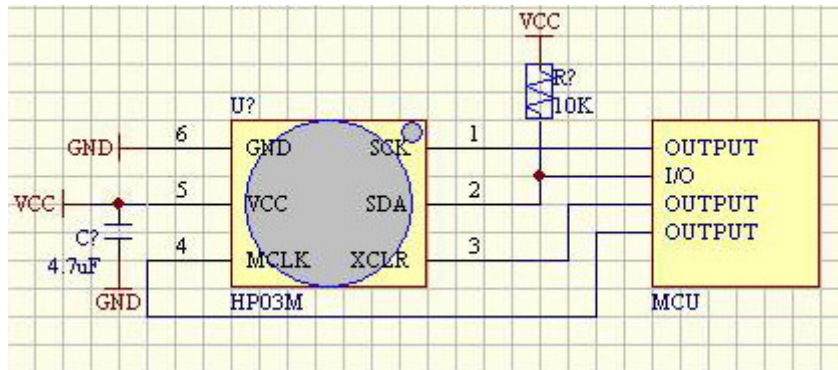
After first power on, the first read data should be disregarded, and only the second value should be used. This can assure that any unstable data after reset can be filtered out.

HP03M

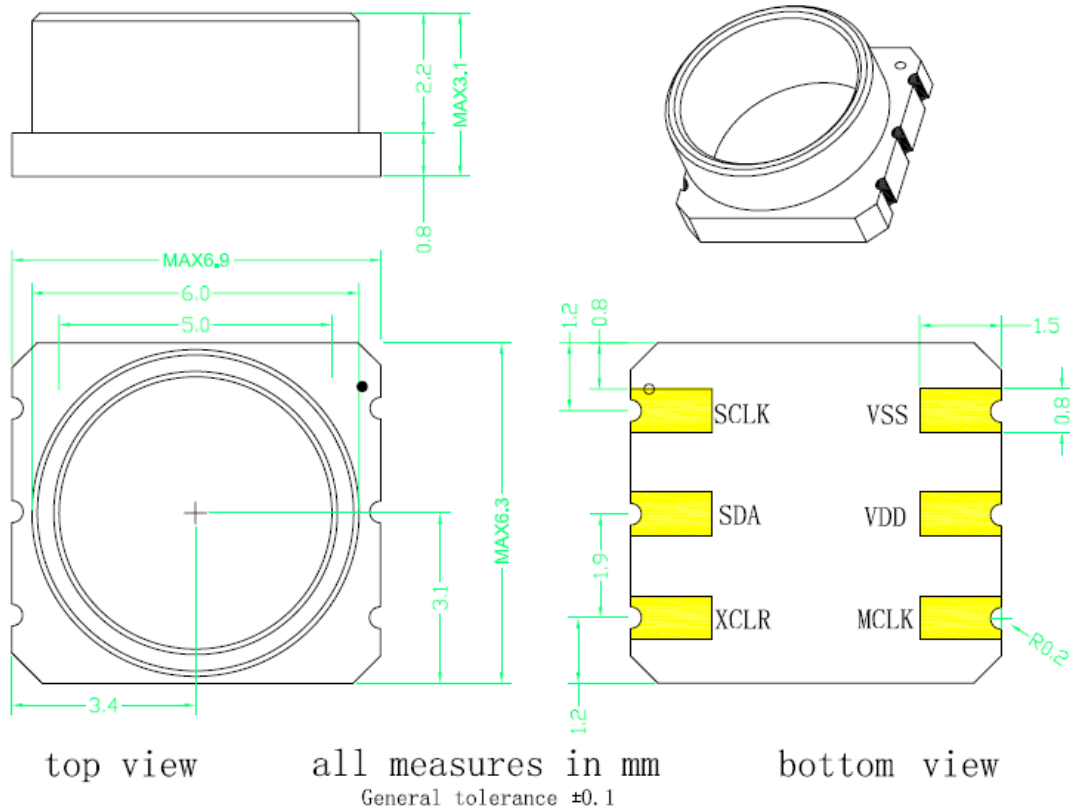
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Typical Application Circuit Diagram:



Mechanical Dimension



Important Notices

Never unplug the module when power is on.

Do not use this product as safety or emergency stop device or in any application where failure of this product could lead in personal injury. Failure to comply with these instructions could result with death or serious injury.

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